

Amendments to the Claims:

The Listing of Claims below represents the sole remaining claims in the Application. Briefly, previously presented claims **1 – 10** are cancelled and previously presented claims **11 – 75** were cancelled in the Response filed 10/17/2005. New claims **76 – 84** are being presented for the first time.

Listing of Claims:

Claims 1 – 10 (cancelled).

Claims 11 – 75 (previously cancelled).

Please add the following **new** claims:

76 (new). A method of making a circuitized substrate, said method comprising:

providing a first dielectric layer having a first surface;

forming a first pattern of conductors and a second pattern of conductors spaced from said first pattern and electrically coupled thereto on said first surface of said first dielectric layer;

forming a common conductive line on said first surface of said first dielectric layer electrically connected to each of said conductors of said second pattern of conductors;

positioning a second dielectric layer substantially over said first and second patterns of conductors; and

thereafter terminating said electrical connections between each of said conductors of said second pattern of conductors and said common conductive line using a laser.

77 (new). The method of claim 76 wherein said second dielectric layer is provided in substantially liquid form and flowed onto said first dielectric layer.

78 (new). The method of claim 77 wherein said second dielectric layer comprises a soldermask.

79 (new). The method of claim 76 further including using said laser to simultaneously provide openings in said second dielectric layer above respective ones of said electrical connections during said terminating of said connections.

80 (new). The method of claim 79 wherein said laser also partially removes some of said first dielectric layer immediately below said electrical connections during said terminating of said connections.

81 (new). A method of making a circuitized substrate, said method comprising:

providing a first dielectric layer having a first surface;

forming a first pattern of conductors and a second pattern of conductors spaced from said first pattern and electrically coupled thereto on said first surface of said first dielectric layer, said forming of said first and second patterns of conductors being accomplished using electrolytic plating;

forming a common conductive line on said first surface of said first dielectric layer electrically connected to each of said conductors of said second pattern of conductors; and

thereafter terminating said electrical connections between each of said conductors of said second pattern of conductors and said common conductive line using a laser.

82 (new). A method of making a circuitized substrate, said method comprising:

providing a first dielectric layer having a first surface;

forming a first pattern of conductors and a second pattern of conductors spaced from said first pattern and electrically coupled thereto on said first surface of said first dielectric layer;

forming a common conductive line on said first surface of said first dielectric layer electrically connected to each of said conductors of said second pattern of conductors;

thereafter terminating said electrical connections between each of said conductors of said second pattern of conductors and said common conductive line using a laser; and

positioning a semiconductor chip on said first dielectric layer and electrically coupling said semiconductor chip to said first pattern of conductors.

83 (new). The method of claim 82 wherein said electrically coupling of said semiconductor chip to said first pattern of conductors is accomplished using a wirebonding operation.

84 (new). The method of claim 82 wherein said semiconductor chip is electrically coupled to said first pattern of conductors using a plurality of solder balls.